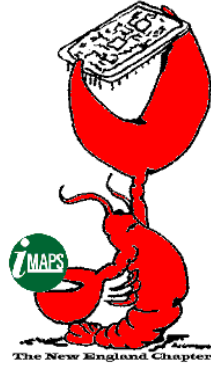
Call for Papers

Deadline for Abstract Submission – December 31, 2011

iMAPS New England – 39th Symposium & Expo

The Largest New England Symposium Dedicated to Microelectronics and Packaging



May 8, 2012

Holiday Inn – Boxborough Woods Conference Center
Boxborough, Massachusetts

The New England Chapter Symposium Technical Program Committee seeks papers that demonstrate how new technologies and applications are expanding and redefining microelectronics. Areas of interests include:

Industry	Advanced Processes & Materials
• Biomedical Electronics	• 3D and High Density Packaging
• Telecom - Microwave	• Photonic/ Optoelectronic packaging
• Military Electronics	• LED Packaging
• Consumer Electronics	• MEMS and Nano Packaging
• Renewable Energy: Fuel Cells, Solar, Wind	• Underfill/ Encapsulants and Adhesives
• Thermal/**Power** Management	• Green packaging / Compliance with RoHS / Electronics recycling
• Manufacturing, Outsourcing & Quality	• Flip-Chip and Bumping: Processes, Reliability
• Software and Firmware Applications	• Wirebonding and Stud Bumping
• High Performance Interconnects and Boards	• Embedded and Integrated Passives
• **Sensor Applications**	• Ceramic, Polymer and Conductive Materials
• Emerging Technologies	• Cu/ Low-K
• **Photovoltaic/Solar**	

Symposium Chair
Roger S. Benson
International Rectifier, Leominster, MA

Please send 250 word abstract to roger.benson@verizon.net or visit us at - www.imapsne.org – for details